

# SH8JB5

### -40V Pch+Pch Power MOSFET

V <sub>DSS</sub>	-40V
R <sub>DS(on)</sub> (Max.)	15.3mΩ
I <sub>D</sub>	±8.5A
P <sub>D</sub>	2.0W

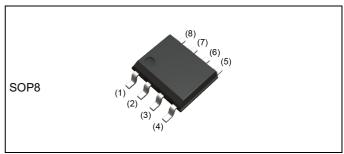
### Features

- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

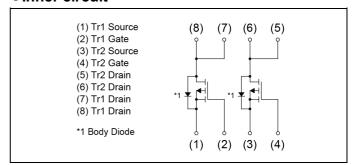
# Application

Switching

### Outline



### •Inner circuit



# Packaging specifications

	Packing	Embossed Tape					
	Reel size (mm)	330					
Туре	Tape width (mm)	12					
	Quantity (pcs)	2500					
	Taping code	TB1					
	Marking	SH8JB5					

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	-40	V	
Continuous drain current	I <sub>D</sub>	±8.5	Α	
Pulsed drain current	I <sub>DP</sub> *1	±34	Α	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *2	-8.5	Α	
Avalanche energy, single pulse	E <sub>AS</sub> *2	5.9	mJ	
Douger discipation (total)	P <sub>D</sub> *3	2.0	W	
Power dissipation (total)	P <sub>D</sub> *4	1.4	] VV	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C	

### ●Thermal resistance

Doromotor	Cymbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion, embient (total)	$R_{thJA}^{*3}$	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R <sub>thJA</sub> *4	-	-	89.2	C/VV

# ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Danamatan	0	0	Values			1.1	
Parameter Symbol		Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = -1mA$	-40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = -1mA referenced to 25°C	-	-22	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	$I_{DSS}$ $V_{DS} = -40V$ , $V_{GS} = 0V$		-	-1	μA	
Gate - Source leakage current	$I_{GSS}$ $V_{GS} = \pm 20V$ , $V_{DS} = 0V$		-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -1mA$	-1.0	-	-2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta  V_{GS(th)}}{\Delta  T_j}$	I <sub>D</sub> = -1mA referenced to 25°C	-	3.7	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = -10V, I <sub>D</sub> = -8.5A	-	12.4	15.3	0	
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -8.5A	-	15.0	18.7	mΩ	
Gate resistance	$R_G$	f = 1MHz, open drain		6.1	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	$V_{DS} = -5V, I_{D} = -8.5A$	12	-	-	S	

2/11

<sup>\*1</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*2</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = -20V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*3</sup> Mounted on a ceramic board (30×30×0.8mm)

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Darameter	Cymahal	Conditions		Unit		
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2870	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -20V	-	295	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	220	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq -20V, V_{GS} = -10V$	-	14	-	
Rise time	<b>t</b> <sub>r</sub> *5	I <sub>D</sub> = -4.25A	-	45	-	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 4.7\Omega$	-	130	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	74	-	

# ● Gate charge characteristics (T<sub>a</sub> = 25°C) < Tr1 and Tr2>

Darameter	Cumbal	Conditions		Values			1 1:4
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total mate above	O *5		V <sub>GS</sub> = -10V	-	51.0	-	
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≈ -20V I <sub>D</sub> = -8.5A		-	25.0	-	0
Gate - Source charge	Q <sub>gs</sub> *5		V <sub>GS</sub> = -4.5V	-	8.1	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	8.1	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

### <Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
Farameter	Symbol	mbol Conditions –		Тур.	Max.	Offic	
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	-	-	-1.67	^	
Pulse forward current	I <sub>SP</sub> *1	1 <sub>a</sub> – 25 C	-	-	-34	A	
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.67A	-	-	-1.2	V	
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = -8.5A, V <sub>GS</sub> = 0V	-	25	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	22	-	nC	



Fig.1 Power Dissipation Derating Curve

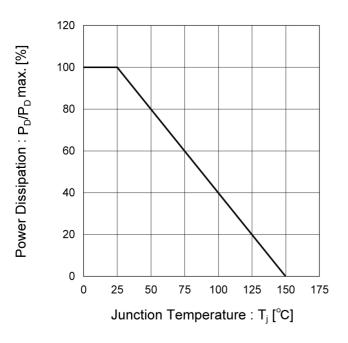
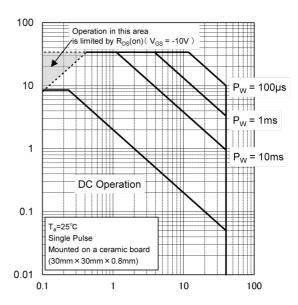


Fig.2 Maximum Safe Operating Area



Drain Current: -l<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

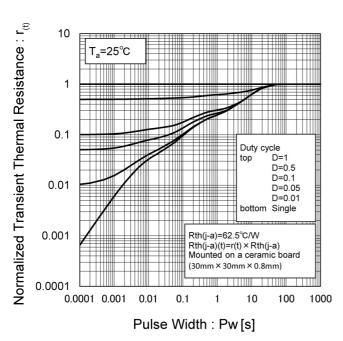


Fig.4 Single Pulse Maximum Power Dissipation

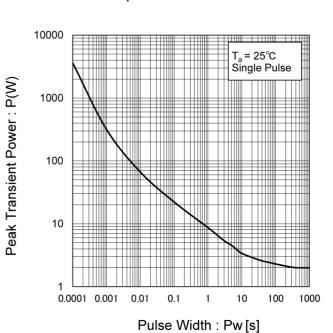


Fig.5 Typical Output Characteristics(I)

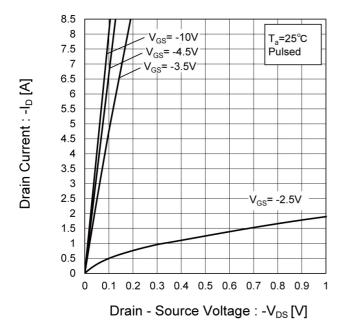
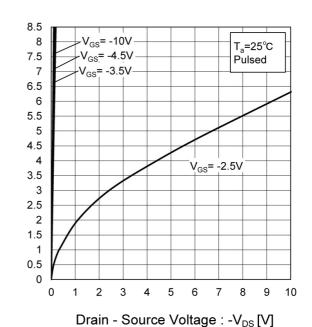


Fig.6 Typical Output Characteristics(II)



Drain Current : -I<sub>D</sub> [A]

Fig.7 Breakdown Voltage vs.

Junction Temperature

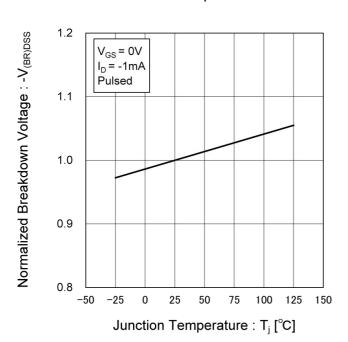




Fig.8 Typical Transfer Characteristics

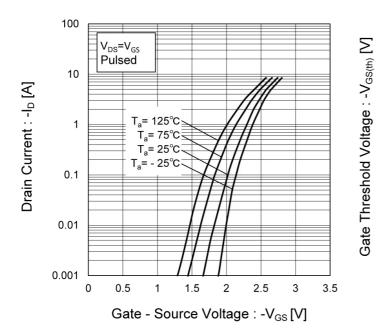


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

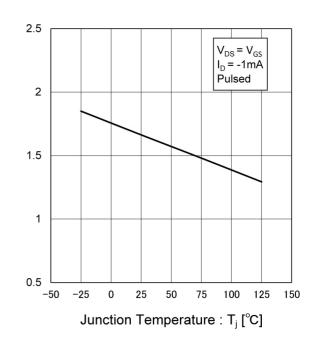


Fig.10 Forward Transfer Admittance vs.
Drain Current

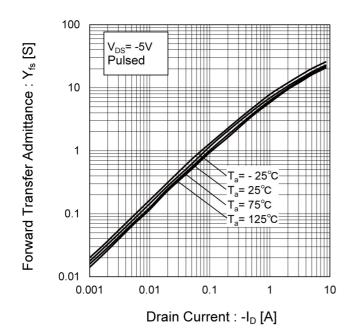


Fig.11 Drain Current Derating Curve

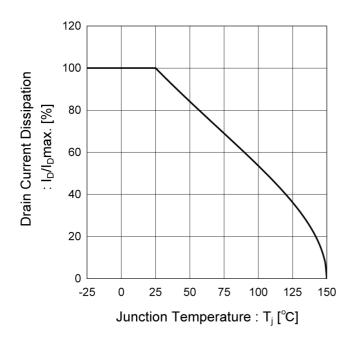


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

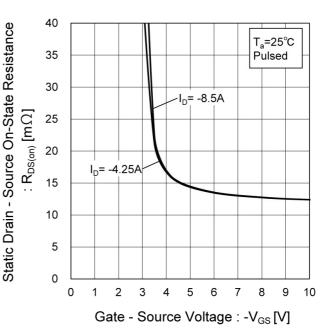


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

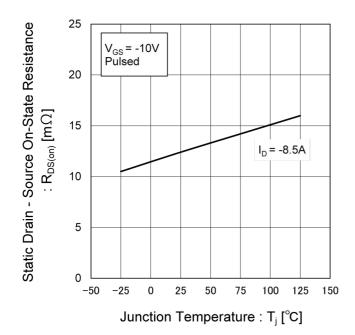


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

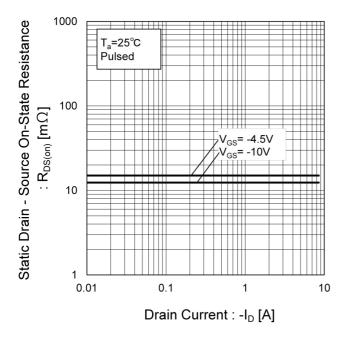


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

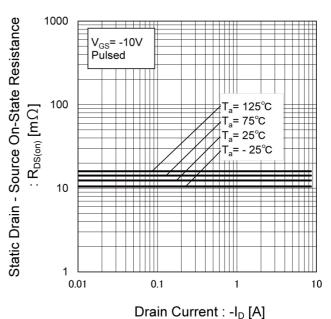


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

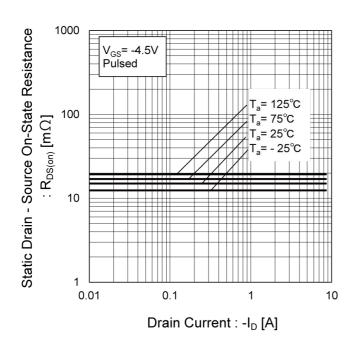


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

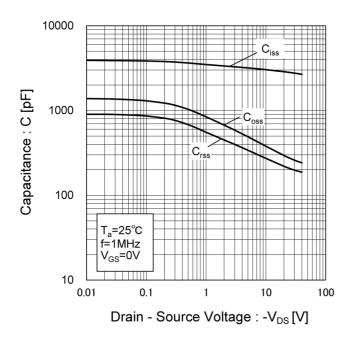


Fig.18 Switching Characteristics

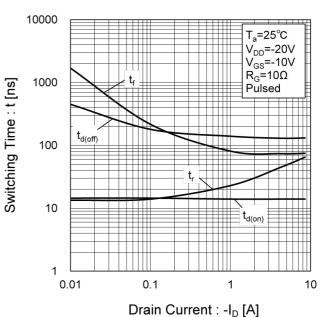


Fig.19 Typical Gate Charge

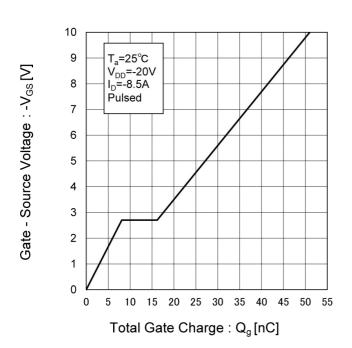
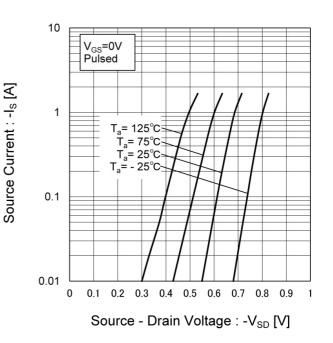


Fig.20 Source Current vs.

Source Drain Voltage



## • Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

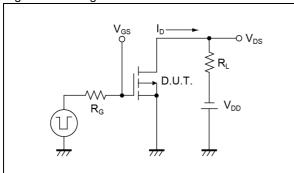


Fig.2-1 Gate Charge Measurement Circuit

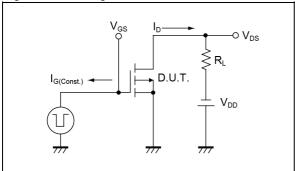


Fig.3-1 Avalanche Measurement Circuit

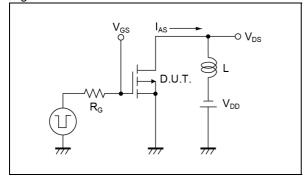


Fig.1-2 Switching Waveforms

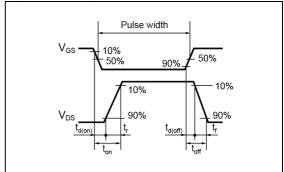


Fig.2-2 Gate Charge Waveform

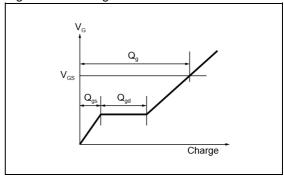
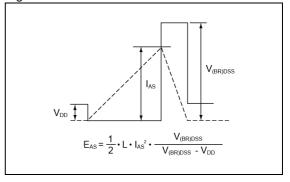
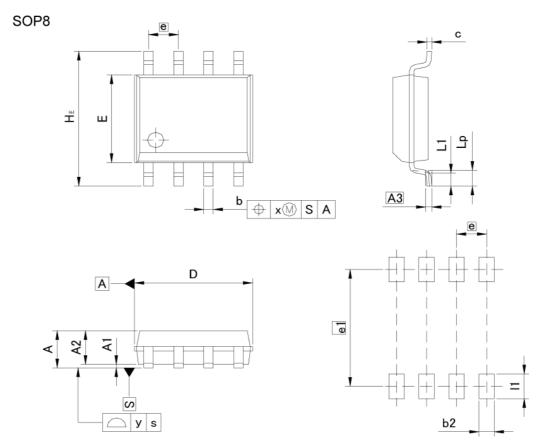


Fig.3-2 Avalanche Waveform



### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	-	1.75	-	0.069
A1	0.	15	0.0	06
A2	1.40	1.60	0.055	0.063
A3	0.	25	0.0	10
b	0.30	0.50	0.012	0.020
С	0.10	0.30	0.004	0.012
D	4.80	5.20	0.189	0.205
Е	3.75	4.05	0.148	0.159
е	1.	27	0.050	
HE	5.70	6.30	0.224	0.248
L1	0.40	0.60	0.016	0.024
Lp	0.65	0.85	0.026	0.033
х	0.15		0.0	06
У	0.10		0.0	04
	NATI TNA	ETERO	TNO	LIEO
DIM	MILIM	ETERS MAY	MINI	HES

DIM	MILIM	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
b2		0.65	-	0.026
e1	5.15		0.2	03
11		1.15	-	0.045

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГУООШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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